

# LMH0026 SD SDI Reclocker with Dual Differential Outputs

Check for Samples: LMH0026

## **FEATURES**

- Supports SMPTE 259M (C) Serial Digital Video Standard
- Supports 270 Mbps Serial Data Rate Operation
- Supports DVB-ASI at 270 Mbps
- Single 3.3V Supply Operation
- 330 mW Typical Power Consumption
- Two Differential, Reclocked Outputs
- Choice of Second Reclocked Output or Low-Jitter, Differential, Data-Rate Clock Output
- Single 27 MHz External Crystal or Reference Clock Input
- Lock Detect Indicator Output
- Output Mute Function for Data and Clock
- Auto/Manual Reclocker Bypass
- Differential LVPECL Compatible Serial Data Inputs and Outputs
- LVCMOS Control Inputs and Indicator Outputs
- 20-Pin HTSSOP Package
- Industrial Temperature Range: -40°C to +85°C
- Footprint Compatible with the LMH0046 and LMH0346

## **APPLICATIONS**

- SDTV Serial Digital Video Interfaces for:
  - Digital Video Routers and Switchers
  - Digital Video Processing and Editing Equipment
  - DVB-ASI Equipment
  - Video Standards and Format Converters

#### DESCRIPTION

The LMH0026 SD SDI Reclocker retimes serial digital video data conforming to the SMPTE 259M (C) standard. The LMH0026 operates at the serial data rate of 270 Mbps and also supports DVB-ASI operation at 270 Mbps.

The LMH0026 retimes the incoming data to suppress accumulated jitter. The LMH0026 recovers the serial data-rate clock and optionally provides it as an output. The LMH0026 has two differential serial data outputs; the second output may be selected as a low-jitter, data-rate clock output. Controls and indicators are: serial clock or second serial data output select, SD indicator output, lock detect output, auto/manual data bypass, and output mute. The serial data inputs, outputs, and serial data-rate clock outputs are differential LVPECL compatible. The CML serial data and serial data-rate clock outputs are suitable for driving  $100\Omega$  differentially terminated networks. The control logic inputs and outputs are LVCMOS compatible.

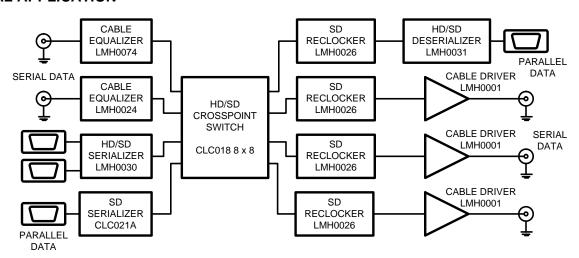
The LMH0026 is powered from a single 3.3V supply. Power dissipation is typically 330 mW. The device is housed in a 20-pin HTSSOP package.

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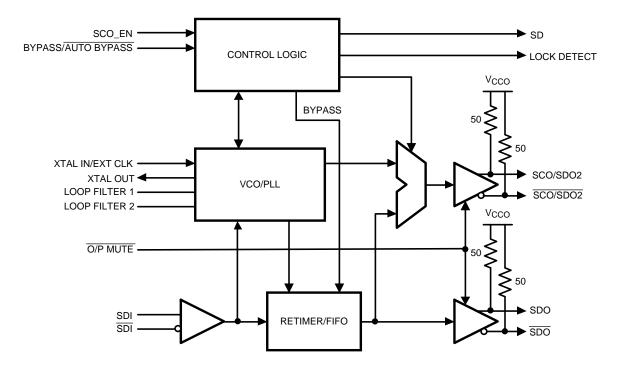
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#### TYPICAL APPLICATION



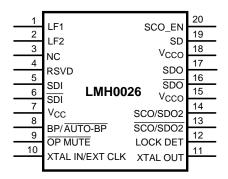
# **Block Diagram**



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## **CONNECTION DIAGRAM**



The exposed die attach pad is the negative electrical terminal for this device. It must be connected to the negative power supply voltage.

Figure 1. 20-Pin HTSSOP

## **PIN DESCRIPTIONS**

Pin	Name	Description
1	LF1	Loop Filter.
2	LF2	Loop Filter.
3	NC	No Connect. Not bonded internally.
4	RSVD	Reserved. Do not connect or connect to ground.
5	SDI	Data Input true.
6	SDI	Data Input complement.
7	V <sub>CC</sub>	Positive power supply input.
8	BYPASS/AUTO BYPASS	Bypass/Auto Bypass mode select. Bypasses reclocking when high. This pin has an internal pulldown.
9	OUTPUT MUTE	Data and Clock Output Mute input. Mutes the output when low. This pin has an internal pullup.
10	XTAL IN/EXT CLK	Crystal or External Oscillator input.
11	XTAL OUT	Crystal Oscillator output.
12	LOCK DETECT	PLL Lock Detect output (active high).
13	SCO/SDO2	Serial Clock or Serial Data Output 2 complement.
14	SCO/SDO2	Serial Clock or Serial Data Output 2 true.
15	V <sub>cco</sub>	Positive power supply input (Output Driver).
16	SDO	Data Output complement.
17	SDO	Data Output true.
18	V <sub>CCO</sub>	Positive power supply input (output driver).
19	SD	SD indicator output. Output is high when locked to 270 Mbps.
20	SCO_EN	Serial Clock or Serial Data 2 Output select. Sets second output to output the clock when high and the data when low. This pin has an internal pulldown.
DAP	V <sub>EE</sub>	Connect exposed DAP to negative power supply (ground).





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

# ABSOLUTE MAXIMUM RATINGS (1)(2)

Supply Voltage (V <sub>CC</sub> -V <sub>EE</sub> )		4.0V
Logic Supply Voltage (Vi)		V <sub>EE</sub> -0.15V to V <sub>CC</sub> +0.15V
Logic Input Current (single input):	Vi = V <sub>EE</sub> -0.15V	−5 mA
	Vi = V <sub>CC</sub> +0.15V	+5 mA
Logic Output Voltage (Vo)		V <sub>EE</sub> -0.15V to V <sub>CC</sub> +0.15V
Logic Output Source/Sink Current		±8 mA
Serial Data Input Voltage (V <sub>SDI</sub> )	V <sub>CC</sub> to V <sub>CC</sub> -2.0V	
Serial Data Output Sink Current (I <sub>SDO</sub> )	24 mA	
Package Thermal Resistance, HTSSOP	$\theta_{JA}$	26.6°C/W
	$\theta_{ m JC}$	2.4°C/W
Storage Temp. Range	·	−65°C to +150°C
Junction Temperature		+150°C
Lead Temperature (Soldering 4 Sec)		+260°C (Pb-free)
ESD Rating (HBM)		7 kV
ESD Rating (MM)		350V
ESD Rating (CDM)		1250V

<sup>(1) &</sup>quot;Absolute Maximum Ratings" are those parameter values beyond which the life and operation of the device cannot be ensured. The stating herein of these maximums shall not be construed to imply that the device can or should be operated at or beyond these values. DC ELECTRICAL CHARACTERISTICS and AC ELECTRICAL CHARACTERISTICS specify acceptable device operating conditions.

#### RECOMMENDED OPERATING CONDITIONS

Supply Voltage (V <sub>CC</sub> -V <sub>EE</sub> )	3.3V ±5%	
Logic Input Voltage	V <sub>EE</sub> to V <sub>CC</sub>	
Differential Serial Input Voltage	800 mV ±10%	
Serial Data or Clock Output Sink	Current (I <sub>SO</sub> )	16 mA max.
Operating Free Air Temperature (T <sub>A</sub> )		-40°C to +85°C

#### DC ELECTRICAL CHARACTERISTICS

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified. (1)(2)

Symbol	Parameter	Conditions	Reference	Min	Тур	Max	Units
$V_{IH}$	Input Voltage High Level		Logic level inputs	2		V <sub>CC</sub>	٧
$V_{IL}$	Input Voltage Low Level			$V_{EE}$		0.8	V
I <sub>IH</sub>	Input Current High Level	$V_{IH} = V_{CC}$			47	65	μA
I <sub>IL</sub>	Input Current Low Level	$V_{IL} = V_{EE}$			-18	-25	μA
V <sub>OH</sub>	Output Voltage High Level	I <sub>OH</sub> = −2 mA	All logic level	2			٧
V <sub>OL</sub>	Output Voltage Low Level	$I_{OL}$ = +2 mA	outputs			V <sub>EE</sub> + 0.6	٧
$V_{SDID}$	Serial Input Voltage, Differential		SDI	200		1600	$mV_{P-P}$
V <sub>CMI</sub>	Input Common Mode Voltage	V <sub>SDID</sub> = 200 mV		V <sub>EE</sub> +1.2		V <sub>CC</sub> -0.2	V

Current flow into device pins is defined as positive. Current flow out of device pins is defined as negative. All voltages are referenced to V<sub>EE</sub> (equal to zero volts).

<sup>(2)</sup> It is anticipated that this device will not be offered in a military qualified version. If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

<sup>(2)</sup> Typical values are stated for:  $V_{CC} = +3.3V$ ,  $T_A = +25$ °C.



# DC ELECTRICAL CHARACTERISTICS (continued)

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified. (1)(2)

Symbol	Parameter	Conditions	Reference	Min	Тур	Max	Units
$V_{SDOD}$	Serial Output Voltage, Differential	100Ω differential load	SDO, SCO	720	800	880	$mV_{P-P}$
$V_{CMO}$	Output Common Mode Voltage	100Ω differential load			V <sub>CC</sub> -		V
I <sub>CC</sub>	Power Supply Current, 3.3V supply, Total	270 Mbps			100		mA

## **AC ELECTRICAL CHARACTERISTICS**

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified. (1)

Symbol	Parameter	Conditions	Reference	Min	Тур	Max	Units
$BR_SD$	Serial Data Rate	SMPTE 259M-C	SDI, SDO		270		Mbps
TOL <sub>JIT</sub>	Serial Input Jitter Tolerance	270 Mbps, (2) (3) (4)	SDI	>6			UI <sub>P-P</sub>
TOL <sub>JIT</sub>	Serial Input Jitter 270 Mbps, (2) (3) (5) Tolerance			>0.6			UI <sub>P-P</sub>
t <sub>JIT</sub>	Serial Data Output Jitter	270 Mbps, (3) (6)	SDO		0.02	0.08	UI <sub>P-P</sub>
BW <sub>LOOP</sub>	Loop Bandwidth	270 Mbps, <0.1dB Peaking			300		kHz
F <sub>CO</sub>	Serial Clock Output Frequency	270 Mbps data rate	SCO		270		MHz
t <sub>JIT</sub>	Serial Clock Output Jitter				2	3	ps <sub>RMS</sub>
	Serial Clock Output Alignment with respect to Data Interval		SDO, SCO	40		60	%
	Serial Clock Output Duty Cycle		SCO	45		55	%
T <sub>ACQ</sub>	Acquisition Time					<sup>(7)(8)</sup> 15	ms
t <sub>r</sub> , t <sub>f</sub>	Input rise/fall time 10%-90%	10%–90%	Logic inputs		1.5	3 1500	ns
t <sub>r</sub> , t <sub>f</sub>	Input rise/fall time	20%-80%	SDI				ps
t <sub>r</sub> , t <sub>f</sub>	Output rise/fall time	10%–90%	Logic outputs		1.5	3	ns
t <sub>r</sub> , t <sub>f</sub>	Output rise/fall time	20%–80%, <sup>(9)</sup>	SDO, SCO		90	130	ps
F <sub>REF</sub>	Reference Clock Frequency				27		MHz
F <sub>TOL</sub>	Reference Clock Frequency Tolerance				±50		ppm

- Typical values are stated for:  $V_{CC}$  = +3.3V,  $T_A$  = +25°C. Peak-to-peak amplitude with sinusoidal modulation per SMPTE RP 184-1996 paragraph 4.1. The test data signal shall be color bars.
- This parameter is ensured by characterization over voltage and temperature limits. Refer to "A1" in Figure 1 of SMPTE RP 184-1996.

  Refer to "A2" in Figure 1 of SMPTE RP 184-1996.

- Serial Data Output Jitter is total output jitter with 0.2 UI<sub>P-P</sub> input jitter.
- Specification is ensured by design.
- Measured from first SDI transition until Lock Detect (LD) output goes high (true).
- $R_L = 100\Omega$  differential.



#### DEVICE DESCRIPTION

The LMH0026 SD SDI Reclocker is used in many types of digital video signal processing equipment. The LMH0026 supports the SMPTE 259M (C) serial digital video standard, with a corresponding serial data rate of 270 Mbps. DVB-ASI data at 270 Mbps may also be retimed. The LMH0026 retimes the serial data stream to suppress accumulated jitter. It provides two low-jitter, differential, serial data outputs. The second output may be selected to output either serial data or a low-jitter serial data-rate clock. Controls and indicators are: serial data-rate clock or second serial data output select, SD indicator output, lock detect output, auto/manual data bypass, and output mute.

Serial data inputs are CML and LVPECL compatible. Serial data and data-rate clock outputs are differential CML and produce LVPECL compatible levels. The output buffer design can drive AC or DC-coupled, terminated  $100\Omega$  differential loads. The differential output level is  $800 \text{ mV}_{P-P}$  ±10% into  $100\Omega$  AC or DC-coupled differential loads. Logic inputs and outputs are LVCMOS compatible.

The device package is an HTSSOP-20 with an exposed die attach pad. The exposed die attach pad is electrically connected to device ground (V<sub>EE</sub>) and is the negative electrical terminal for the device. This terminal must be connected to the negative power supply or circuit ground.

#### Serial Data Inputs, Serial Data and Clock Outputs

#### **SERIAL DATA INPUT AND OUTPUTS**

The differential serial data input, SDI, accepts 270 Mbps serial digital video data. The serial data input is differential LVPECL compatible. The input is intended to be DC interfaced to devices such as the LMH0074 adaptive cable equalizer. The input is not internally terminated or biased. The input may be AC-coupled if a suitable input bias voltage is provided. Figure 2 shows the equivalent input circuit for SDI and SDI.

The LMH0026 has two, retimed, differential, serial data outputs, SDO and SCO/SDO2. These outputs provide low jitter, differential, retimed data to devices such as the LMH0001 or LMH0002 cable driver. Output SCO/SDO2 is multiplexed and can provide either a second serial data output or a serial data-rate clock output. Figure 3 shows the equivalent output circuit for SDO, SDO, SCO/SDO2, and SCO/SDO2.

The SCO\_EN input controls the operating mode for the SCO/SDO2 output. When the SCO\_EN input is high the SCO/SDO2 output provides a serial data-rate clock. When SCO\_EN is low, the SCO/SDO2 output provides retimed serial data.

Both differential serial data outputs, SDO and SCO/SDO2, are muted when the OUTPUT  $\overline{\text{MUTE}}$  input is a logic low level. SCO/SDO2 also mutes when the Bypass mode is activated when this output is operating as the serial clock output. When muted, SDO and  $\overline{\text{SDO}}$  (or SDO2 and  $\overline{\text{SDO2}}$ ) will assume opposite differential output levels. The CML serial data outputs are differential LVPECL compatible. These outputs have internal 50 $\Omega$  pull-ups and are suitable for driving AC or DC-coupled,  $100\Omega$  center-tapped, AC grounded or  $100\Omega$  un-center-tapped, differentially terminated networks.

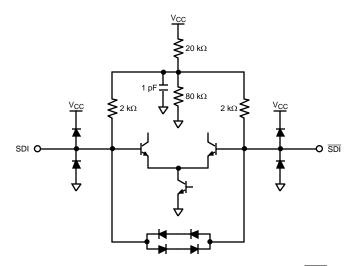


Figure 2. Equivalent SDI input Circuit (SDI, SDI)



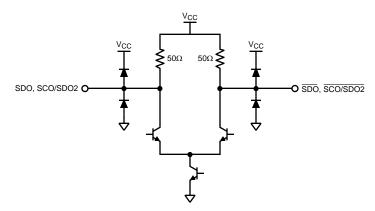


Figure 3. Equivalent SDO Output Circuit (SDO, SDO, SCO/SDO2, SCO/SDO2)

#### **SERIAL DATA CLOCK/SERIAL DATA 2 OUTPUT**

The Serial Data Clock/Serial Data 2 Output is controlled by the SCO\_EN input and provides either a second retimed serial data output or a low jitter differential clock output appropriate to the serial data rate being processed. When operating as a serial clock output, the rising edge of the clock will be positioned within the corresponding serial data bit interval within 10% of the center of the data interval.

Differential output SCO/SDO2 functions as the second serial data output when the SCO\_EN input is a logic-low level. This output functions as the serial data-rate clock output when the SCO\_EN input is a logic-high level. The SCO\_EN input has an internal pull-down device and the default state of SCO\_EN is low (serial data output 2 enabled). SCO/SDO2 is muted when the OUTPUT MUTE input is a logic low level. When the Bypass mode is activated and this output is functioning as a serial clock output, the output will also be muted. If an unsupported data rate is used while in Auto Bypass mode with this output functioning as a serial clock output, the output is invalid.

## **Control Inputs and Indicator Outputs**

#### **LOCK DETECT**

The Lock Detect (LD) output, when high, indicates that data is being received and the PLL is locked. LD may be connected to the OUTPUT MUTE input to mute the data and clock outputs when no data signal is being received. Note that when the Bypass/Auto Bypass input is set high, Lock Detect will remain low. See Table 1.

#### **OUTPUT MUTE**

The OUTPUT MUTE input, when low, mutes the serial data and clock outputs. It may be connected to Lock Detect or externally driven to mute or un-mute the outputs. If OUTPUT MUTE is connected to LD, then the data and clock outputs are muted when the PLL is not locked. This function overrides the Bypass function: see Table 1. OUTPUT MUTE has an internal pull-up device to enable the output by default.

## **BYPASS/AUTO BYPASS**

The Bypass/Auto Bypass input, when high, forces the device to output the data without reclocking it. When this input is low, the device automatically bypasses the reclocking function when the device is in an unlocked condition or the detected data rate is a rate which the device does not support. Note that when the Bypass/Auto Bypass input is set high, Lock Detect will remain low. See Table 1. BYPASS/AUTO BYPASS has an internal pull-down device.

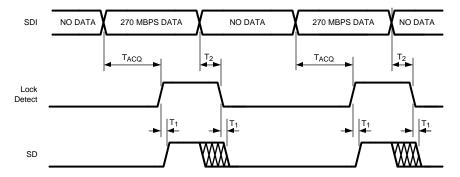


#### **Table 1. Control Functionality**

LOCK DETECT	OUTPUT MUTE	BYPASS/AUTO BYPASS	DEVICE STATUS
0	1	X	PLL unlocked, reclocker bypassed
1	1	0	PLL locked to supported data rate, reclocker not bypassed
X	0	Χ	Outputs muted
0	LOCK DETECT	Х	Outputs muted
1	LOCK DETECT	0	PLL locked to supported data rate, reclocker not bypassed

#### SD

The SD output indicates that the LMH0026 is locked and processing SD data rates. It may be used to control another device such as the LMH0002 cable driver. When this output is high it indicates that the data rate is 270 Mbps. The SD output is a registered function and is only valid when the PLL is locked and the Lock Detect output is high. When the PLL is not locked (the Lock Detect output is low), the SD output defaults to low. The SD output is undefined for a short time after lock detect assertion or de-assertion due to a data change on SDI. See Figure 4 for a timing diagram showing the relationship between SDI, Lock Detect, and SD.



T<sub>ACO</sub> = Acquisition Time, defined in the AC Electrical Characteristics Table

Figure 4. SDI, Lock Detect, and SD Timing

#### SCO EN

Input SCO\_EN enables the SCO/SDO2 differential output to function either as a serial data-rate clock or second serial data output. SCO/SDO2 functions as a serial data-rate clock when SCO\_EN is high. This pin has an internal pull-down device. The default state (low) enables the SCO/SDO2 output as a second serial data output.

#### CRYSTAL OR EXTERNAL CLOCK REFERENCE

The LMH0026 uses a 27 MHz crystal or external clock signal as a timing reference input. A 27 MHz parallel resonant crystal and load network may be connected to the XTAL IN/EXT CLK and XTAL OUT pins. Alternatively, a 27 MHz LVCMOS compatible clock signal may be input to XTAL IN/EXT CLK. Parameters for a suitable crystal are given in Table 2.

T<sub>1</sub> = Time from Lock Detect assertion or deassertion until SD output is valid, typically 37 ns (one 27 MHz clock period)

 $T_2$  = Time from SDI input change until Lock Detect de-assertion, 1 ms maximum. SD output is not valid during this time.

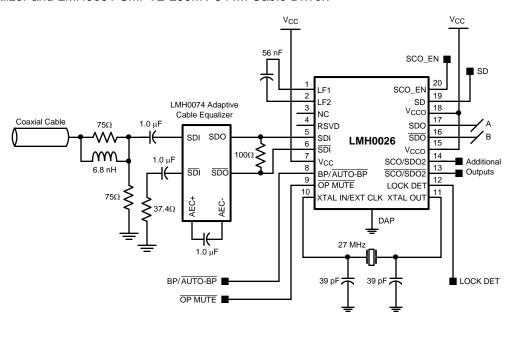


## **Table 2. Crystal Parameters**

Parameter	Value
Frequency	27 MHz
Frequency Stability	±50 ppm @ recommended drive level
Operating Mode	Fundamental mode, Parallel Resonant
Load Capacitance	20 pF
Shunt Capacitance	7 pF
Series Resistance	40Ω max.
Recommended Drive Level	100 μW
Maximum Drive Level	500 μW
Operating Temperature Range	−10°C to +60°C

## **APPLICATION INFORMATION**

Figure 5 shows an application circuit for the LMH0026 along with the LMH0074 SMPTE 259M / 344M Adaptive Cable Equalizer and LMH0001 SMPTE 259M / 344M Cable Driver.



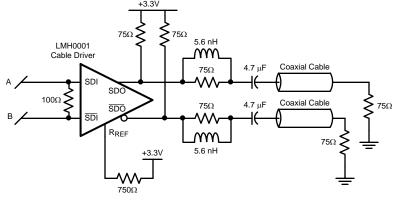


Figure 5. Application Circuit



The LMH0026 inputs are LVPECL compatible. The LMH0026 has a wide input common mode range and in most cases the input should be DC coupled. For DC coupling, the inputs must be kept within the common mode range specified in DC ELECTRICAL CHARACTERISTICS. Figure 5 shows an example of a DC coupled interface between the LMH0074 cable equalizer and the LMH0026. The LMH0074 output common mode voltage and voltage swing are within the range of the input common mode voltage and voltage swing of the LMH0026. All that is required is a  $100\Omega$  differential termination as shown. The resistor should be placed as close to the LMH0026 input as possible. If desired, this network may be terminated with two  $50\Omega$  resisters and a center tap capacitor to ground in place of the single  $100\Omega$  resistor.

The LMH0026 outputs are LVPECL compatible. SDO is the primary data output and SCO/SDO2 is a second output that may be set as the serial clock or a second data output. Both outputs are always active. The LMH0026 output should be DC coupled to the input of the receiving device as long as the common mode ranges of both devices are compatible. Figure 5 shows an example of a DC coupled interface between the LMH0026 and LMH0001 cable driver. All that is required is a  $100\Omega$  differential termination as shown. The resistor should be placed as close to the LMH0001 input as possible. If desired, this network may be terminated with two  $50\Omega$  resisters and a center tap capacitor to ground in place of the single  $100\Omega$  resistor.

The external loop filter capacitor (between LF1 and LF2) should be 56 nF. This is the only supported value; the loop filter capacitor should not be changed.

BYPASS/AUTO BYPASS has an internal pulldown to enable Auto Bypass mode by default. This pin may be pulled high to force the LMH0026 to bypass all data.

OUTPUT MUTE has an internal pullup to enable the outputs by default. This pin may be pulled low to mute the outputs.

The XTAL IN/EXT CLK and XTAL OUT pins are shown with a 27 MHz crystal and the proper loading. The crystal should match the parameters described in Table 2. Alternately, a 27MHz LVCMOS compatible clock signal may be input to XTAL IN/EXT CLK.

The active high LOCK DETECT output provides an indication that proper data is being received and the PLL is locked.

The SD output may be used to drive the SD/HD pin of an SDI cable driver (such as the LMH0002) in order to properly set the cable driver's edge rate for SMPTE compliance. It defaults to low when the LMH0026 is not locked.

SCO\_EN has an internal pulldown to set the second output (SCO/SDO2) to output data. This pin may be pulled high to set the second output as a serial clock.

The ground connection for the LMH0026 is through the large exposed DAP. The DAP must be connected to ground for proper operation of the LMH0026.



# **REVISION HISTORY**

Changes from Revision A (April 2013) to Revision B			
•	Changed layout of National Data Sheet to TI format		10

www.ti.com 2-May-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
LMH0026MH/NOPB	Active	Production	HTSSOP (PWP)   20	73   TUBE	Yes	SN	Level-3-260C-168 HR	-40 to 85	L026

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

# PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

## **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
LMH0026MH/NOPB	PWP	HTSSOP	20	73	495	8	2514.6	4.06

PWP (R-PDSO-G20)

# PowerPAD™ PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
- This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <a href="http://www.ti.com">http://www.ti.com</a>.

  E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- E. Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments.





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